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DATA SHEET

PART NO.: L-T670KRCT-PO

REV: <u>A / 1</u>

CUSTOMER'S APPROVAL :

DRAWING NO. : DS-7A-06-0077

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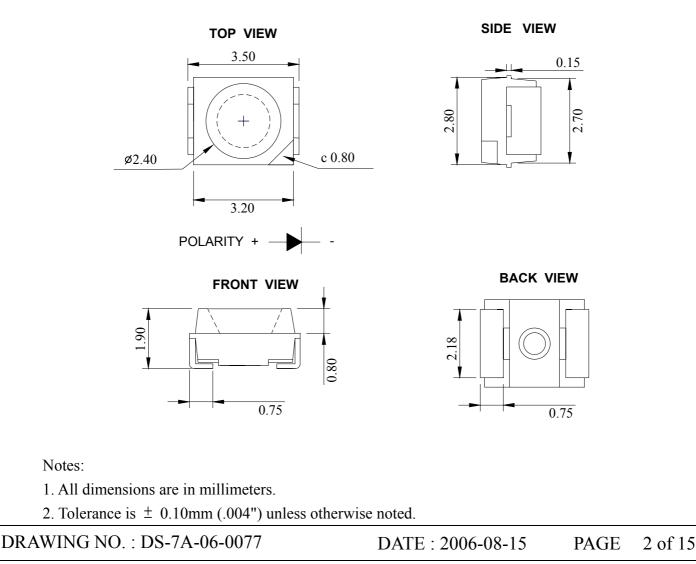


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Features

- * Top view, Wide view angle, Red color PLCC 2 package SMD LED.
- * EIA STD package, packing in 8mm tape on 7" diameter reels (ANSI/EIA-481-B-2001).
- * Compatible with automatic Pick & Place equipment.
- * Compatible with IR Reflow soldering and TTW soldering.
- * Pb free product.
- Application
 - * Backlighting (LCD, Switches, keys, displays, illuminated advertising)
 - * Emergency lighting / Signal and symbol luminaries.
- Package Outline Dimensions





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• CHIP MATERIALS

- * Dice Material : AlInGaP
- * Light Color : Red
- * Lens Color : Water Clear

• Absolute Maximum Ratings(Ta=25°C)

Symbol	Parameter	Rating	Unit	
Pd	Power Dissipation	55	mW	
Ipf	Peak Forward Current	100	mA	
	(1/10 Duty Cycle, 0.1ms Pulse Width)			
IF	Continuous Forward Current	20	mA	
VR	Reverse Voltage	5	V	
ESD	Electrostatic Discharge Threshold (HBM) ^{Note A}	2000	V	
Topr	Operating Temperature Range	-40 ~ + 85	°C	
Tstg	Storage Temperature Range	-40 ~ + 100	°C	
Tsld	Soldering Toma antique (On a times MAX)	Reflow Soldering:240°C (for 10seconds)		
1510	Soldering Temperature (One times MAX.)	Hand Soldering:350°C (for 3 seconds		

Note A :

HBM : Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

• Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Luminous Intensity	IV	60	100		mcd	IF=20mA
Viewing Angle	2 0 1/2		120		Deg	
Dominant Wavelength	λD		630		nm	IF=20mA
Spectrum Radiation	Δλ	15	20	25	12.122	IF=20mA
Bandwidth	ΔΛ	13	20	23	nm	IF-20IIIA
Forward Voltage	VF	1.8		2.8	V	IF = 20mA
Reverse Current	IR			10	μA	VR = 5V

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Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. Caution in ESD :

Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

4. Major standard testing equipment by "Instrument System" Model : CAS140B Compact Array Spectrometer and "KEITHLEY" Source Meter Model : 2400.

• Typical Electro-Optical Characteristics Curves

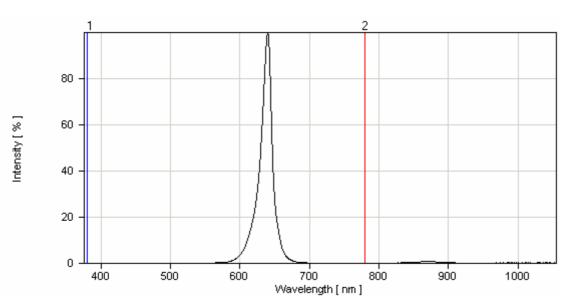


Fig.1 Relative Intensity vs. Wavelength

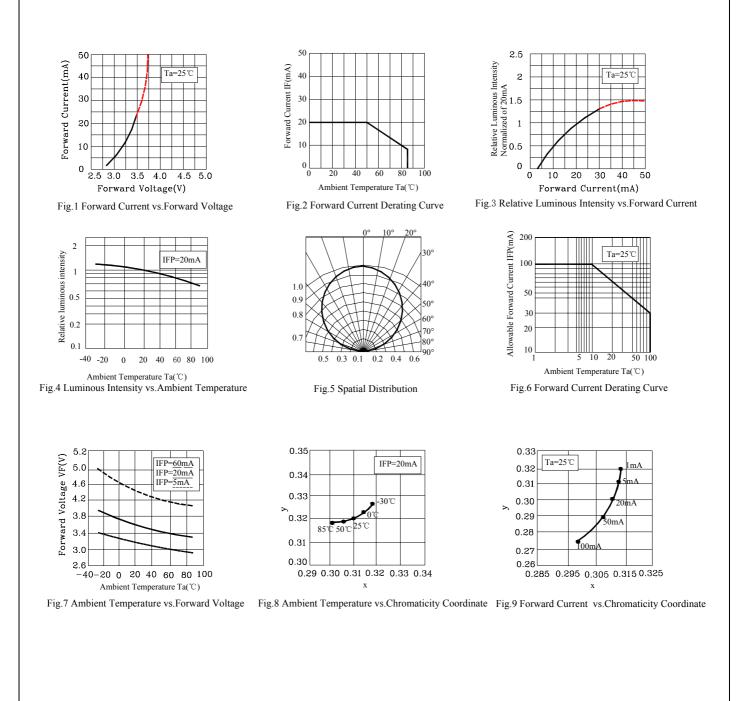


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• Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)



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• Bin Code List

Luminous Intensity(IV), Unit:mcd@20mA				
Bin Code	Min	Max		
P09	70	80		
P10	80	100		
P11	100	125		
P12	125	155		

Tolerance of each bin are $\pm 15\%$

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SURFACE MOUNT DEVICE LED

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	Label	Expl	lanation
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CUS. PART NO: To be denominated. CUSTOMER: To be denominated.

PART NO: Refer to P15

BATCH: P16 (actual code will be base on page 6 specification).

P16--- Luminous Intensity Code

LOT NO: E L S 6 8 0001 B C D E А F A---E: For series number B---L: Local F: Foreign C---S: SMD D---Year E---Month F---SPEC. PACKING QUANTITY OF BAG : 2000pcs for T670 series 2000pcs for T650 series 2000pcs for S020 series DATE CODE: 2006 06 08 G Η Ι G---- Year H--- Month I --- Day

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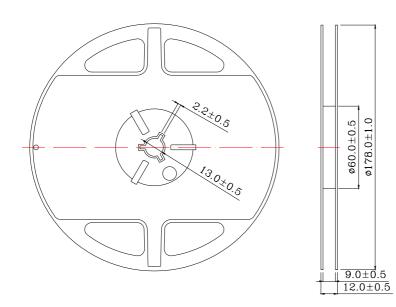
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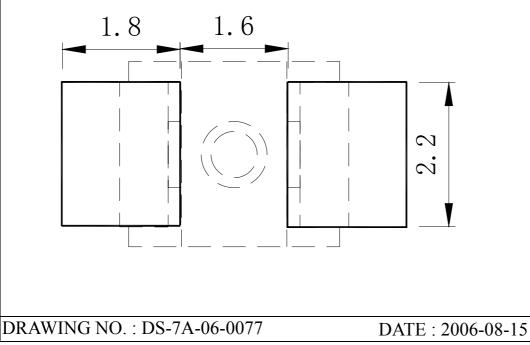
• Reel Dimensions



Notes:

- 1. Taping Quantity : 2000pcs
- 2. The tolerances unless noted is ± 0.1 mm, Angle $\pm 0.5^{\circ}$, Unit: mm.

Suggest Soldering Pad Dimensions

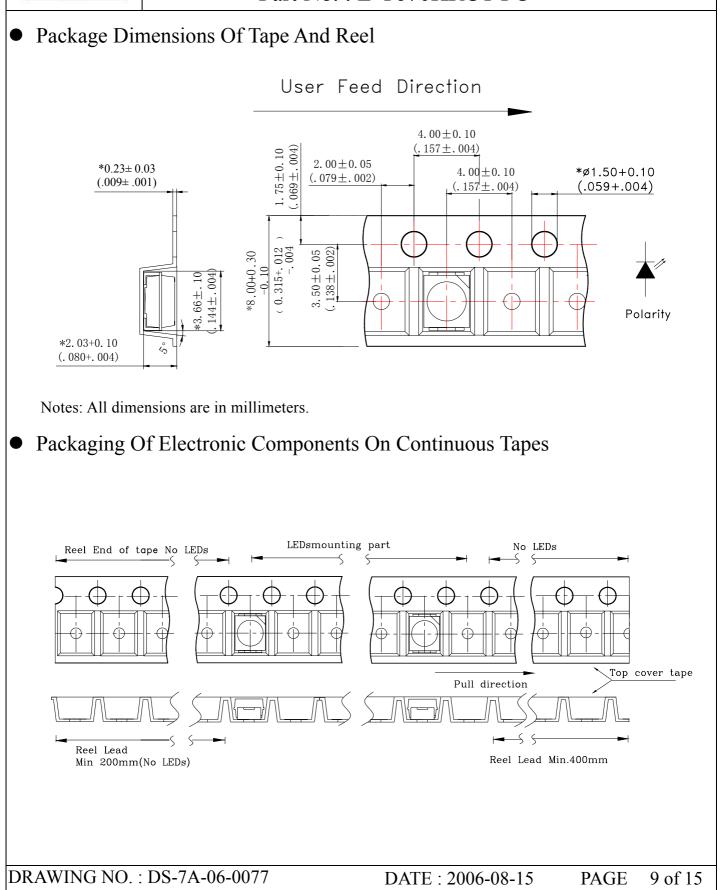


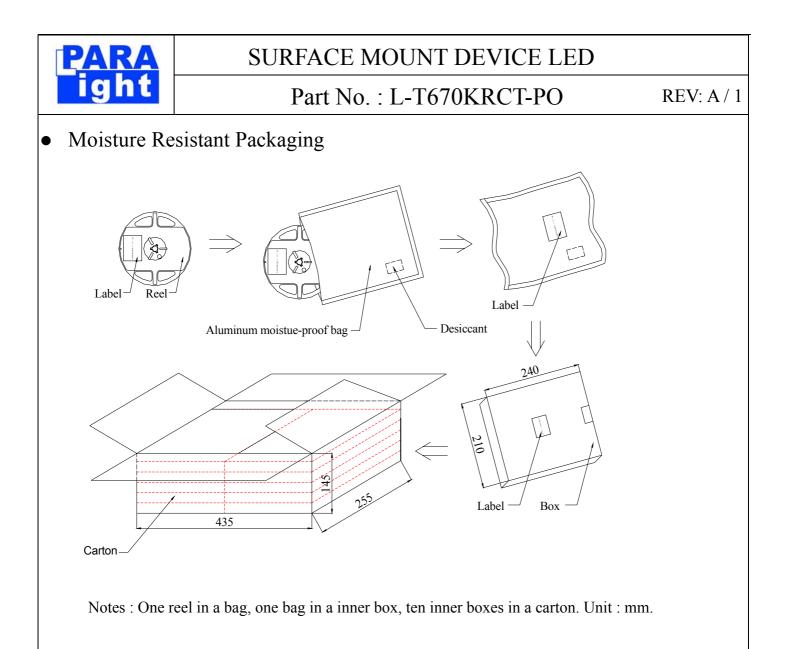
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Cleaning

- * If cleaning is required, use the following solutions for less than 1 minute and less than 40° C.
- * Appropriate chemicals: isopropyl alcohol. (When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.)
- * Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as ultrasonic power and the assembled condition. Before cleaning, a pre-test should be confirm whether any damage to the LEDS will occur.

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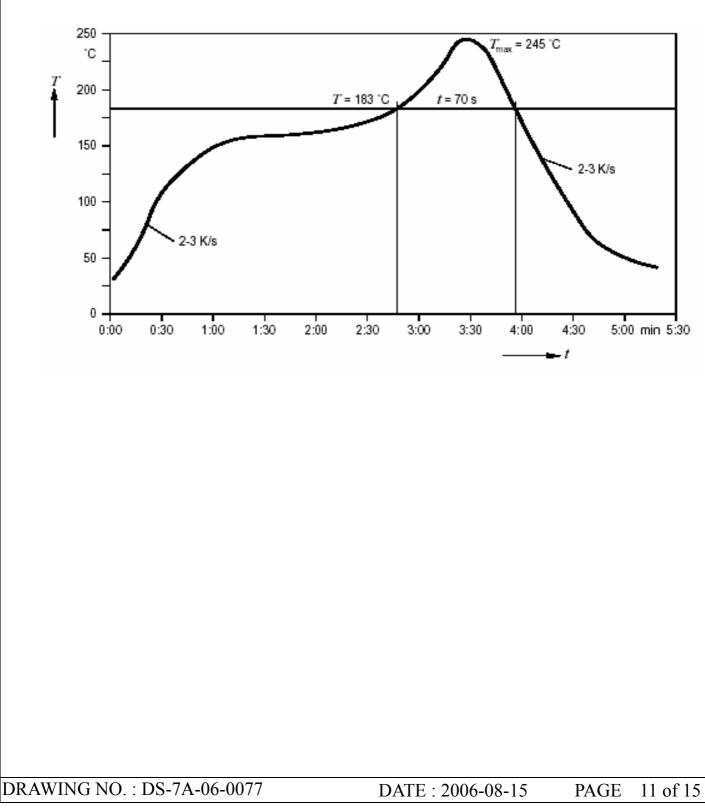
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• Suggest Sn/Pb IR Reflow Soldering Profile Condition:





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CAUTIONS

1. Static Electricity:

* Static electricity or surge voltage damages the LEDs.

It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.

* All devices, equipment and machinery must be properly grounded.

It is recommended that measures be taken against surge voltage to the equipment that mounts the LEDs. * When inspecting the final products in which LEDs were assembled, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by a light-on test or a VF test at a lower current (blew 1mA is recommended).

* Damaged LEDs will show some unusual characteristics such as the leak current remarkably increases, the forward voltage becomes lower, or the LEDs do not light at the low current.

Criteria: (VF>2.0V, at IF=0.5m A)

2. Storage :

* Before opening the package :

The LEDs should be kept at 30°C or less and 85%RH or less. When storing the LEDs, moisture proof packaging with absorbent material (silica gel) is recommended.

* After opening the package :

The LEDs should be kept at 30°C or less and 70%RH or less. The LEDs should be soldered within 168 hours (7 days) after opening the package. If unused LEDs remain, they should be stored in moisture proof packages, such as sealed containers with packages of moisture absorbent material (silica gel). It is also recommended to return the LEDs to the original moisture poof bag and to reseal the moisture proof bag again.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should e performed using the following conditions. Baking treatment: more than 24hours at $65\pm5^{\circ}$ C.

* Please avoid rapid transitions in ambient temperature in high humidity environments where condensation may occur.

3. Soldering:

Do not apply any stress to the LED lens during soldering while the LED is at high temperature. Recommended soldering condition.

* Reflow Soldering :

Pre-heat 120~150°C, 120sec. MAX., Peak temperature : 240°C Max. Soldering time : 10 sec Max.

* Soldering Iron : (Not recommended)

Temperature350°C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering.

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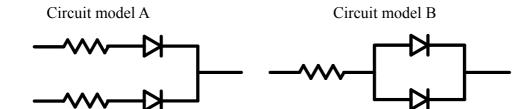
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4. Drive Method



(A)Recommended circuit.

(B)The difference of brightness between LED's could be found due to the Vf-If characteristics of LED.

- 5. Reliability
 - 1、 Criteria For Judging The Damage

Item	Symbol	Test Conditions	Criteria for Judgement		
Itelli	Symbol	Test Conditions	MIN.	Max.	
Forward Voltage	VF	IF=20mA	-	U.S.L.*)×1.1	
Reverse Current	IR	VR=5V	-	U.S.L.*)×2.0	
Luminous Intensity	IV	IF=20mA	L.S.L**)×0.7	-	

*) U.S.L.: Upper Standard Level

**) L.S.L: Lower Standard Level

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2、Test Items And Results

Test Item	Reference Standard	Test Condition	Note	Numbe of Damag d
Resistance to Soldering Heat (Reflow Soldering)	JEITA ED-4701300 301	Tsld=240℃,10sec. (Pre treatment 30 ℃,70%,168hrs)	2times	0/50
Solder ability (Reflow Soldering)	JEITA ED-4701300 303	Tsld=215℃,3sec. (Lead Solder)	1time over 95%	0/50
Thermal Shock	JEITA ED-4701300 307	0°C ~ 100°C 15sec. 15sec.	20cycles	0/50
Temperature Cycle	JEITA ED-4701100 105	-40℃ ~25℃~100℃~25℃ 30min. 5min. 30min. 5min.	100cycle s	0/50
Moisture Resistance Cyclic	JEITA ED-4701200 203	25℃ ~65℃~-10℃ 90%RH 24hrs./1cycle	10cycles	0/50
High Temperature Storage	JEITA ED-4701200- 201	Ta=100°C	1000hrs.	0/50
Temperature Humidity Storage	JEITA ED-4701100 103	Ta=60℃,RH=90%	1000hrs.	0/50
Low Temperature Storage	JEITA ED-4701200 202	Ta=-40°C	1000hrs.	0/50
Steady State Operating Life Condition1		Ta=25°C,IF=20mA	1000hrs.	0/50
Steady State Operating Life Condition2		Ta=25℃,IF=35mA	500hrs.	0/50
Steady State Operating Life of High Temperature		Ta=85℃,IF=5mA	1000hrs.	0/50
Steady State Operating Life of High Humidity Heat		Ta=60℃,RH=90%,IF=15mA	500hrs.	0/50
Steady State Operating Life of Low Temperature		Ta=-30°C,IF=20mA	1000hrs.	0/50
Vibration	JEITA ED-4701400 403	100~2000~100HzSweep 4min.200m/s ² 3direction,4cycles	48min	0/50
Substrate Bending	JEITA ED-4702	3 mm, 5 ± 1 sec	1 time	0/50
Stick	JEITA ED-4702	$5N,10\pm1sec$	1time	0/50

The appearance and specifications of the product may be modified for improvement without notice.

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• PART NO. SYSTEM : $L - \underline{T \ 67 \ 0 \ X \ X \ T} - \underline{X \ X \ X \ X}$	XXXX : Special specification for customer
	T : Taping for 7 inch reel TC : Taping for 13 inch reel
	Lens color C : Water Clear W : White Diffused T : Color Transparent D : Color Diffused
	KY : 9mil AlInGap 590nm Super Yellow KR : 9mil AlInGap 625 nm Super Red TR : 14mil AlInGap 630 nm Super Red TY: 14mil AlInGap590 nm Super Yellow LB : InGaN ITO 粗化 470nm Blue LG : InGaN ITO 粗化 520nm Green W : InGaN + YAG White color
	0 : Single chip 1/2 : Super thin single chip 5/6 : Dual chip F : Three chip(Full color)
C : PCB Top T :PLCC Top S : Side View	View Type
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